



Trans. JIEP shall keep flying high in the future

Here, we welcome you to the third volume of Transactions of The Japan Institute of Electronics Packaging (Trans. JIEP). I believe that this English version journal, Trans. JIEP, has really taken off, and that this publication will continue to develop a sustained growth trajectory. This is due to the hard work of many people, including the authors, reviewers/referees, editorial committee members, society members, the secretariat, and so on. Again, I would like to make a most cordial acknowledgment to all the persons involved in publishing Trans. JIEP. I hope that this Trans. JIEP remains a viable and variable medium to transmit and receive information and knowledge on microelectronics packaging technologies toward and from the rest of the world. Fortunately, since we are in the most active region of microelectronics industry, we have many opportunities to develop and create novel technologies; it is a great advantage for us. So, let us send information on your important and remarkable achievements through Trans. JIEP from Asia to the rest of the world. Our next aim is to publish this Trans. JIEP several times per year. To this end, submissions of your manuscripts are indispensable, and I would ask you to continue to submit your most interesting and exciting papers to Trans. JIEP, now and into the future.

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